

DESCRIPTION:

With high ability to withstand the shock loading of large current, **VSA16/VSB16** triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



MAIN FEATURES

Symbol	Value	Unit
I _{T(RMS)}	16	Α
V _{DRM} /V _{RRM}	600/800/1200	V



ABSOLUTE MAXIMUM RATINGS

P	arameter	Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40-150	$^{\circ}\!\mathbb{C}$
Operating junction temperature range		Tj	-40-125	$^{\circ}\!\mathbb{C}$
Repetitive peak off	-state voltage (Tj=25℃)	VDRM	600/800/1200	V
Repetitive peak reverse voltage (T _j =25℃)		VRRM	600/800/1200	V
Non repetitive surge peak Off-state voltage		V _{DSM}	V _{DRM} +100	V
Non repetitive peak reverse voltage		V _{RSM}	V _{RRM} +100	V
TO-220A(Ins)/ TO-220F(Ins) (Tc=75°C) TO-220B(Non-Ins)/ TO-220C (Tc=95°C) TO-262 (Tc=70°C)		I _{T(RMS)}	16	А
Non repetitive surge peak on-state current (full cycle, F=50Hz)		Ітѕм	160	Α

Vseei Semiconductor Co., Ltd



I ² t value for fusing (tp=10ms)	l ² t	128	A ² s
Critical rate of rise of on-state current $(I_G = 2 \times I_{GT})$	dl/dt	50	A/µs
Peak gate current	Івм	4	Α
Average gate power dissipation	P _{G(AV)}	1	W
Peak gate power	P _{GM}	5	W

ELECTRICAL CHARACTERISTICS (T_j =25 $^{\circ}$ C unless otherwise specified)

3 Quadrants

Symbol	Test Condition	Quadrant		Value				Unit
	rest Condition			BW	CW	sw	TW	Oint
Іст	V 40V D 000	I - II -III	MAX	50	35	10	5	mA
V _{GT}	V _D =12V R _L =33Ω	I - II -III	MAX	1.3				V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	I - II -III	MIN	0.2			V	
IL	I _G =1.2I _{GT}	I -III	MAX	70	50	30	15	mΛ
		II	IVIAA	80	60	40	20	mA
lμ	I _T =100mA		MAX	60	40	25	15	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	1000	500	200	100	V/µs

4 Quadrants

Symbol	Test Condition	Quadrant		Va	I I mit	
				В	С	Unit
l		I - II -III	I - II - III MAX	50	25	mA
Igt	V _D =12V R _L =33Ω	IV		70	50	
V _{GT}		ALL	MAX	1.5		V
V _{GD}	$V_D = V_{DRM} T_j = 125$ °C $R_L = 3.3$ ΚΩ	ALL	MIN	0.2		V
IL	I _G =1.2I _{GT}	I -III-IV	MAV	70	50	m 1
		II	MAX	100	80	mA
lн	I _T =100mA		MAX	60	40	mA
dV/dt	V _D =2/3V _{DRM} Gate Open T _j =125℃		MIN	500	200	V/µs

Vseei Semiconductor Co., Ltd



STATIC CHARACTERISTICS

Cumbal	Parameter		V	I In:i4		
Symbol			-600V	-800V	-1200V	Unit
V _{TM}	I _{тм} =22.5A tp=380µs	Tj=25℃	1.5			V
I _{DRM}	V _D =V _{DRM} V _R =V _{RRM}	Tj=25℃	5	5	10	μA
I _{RRM}		T _j =125℃	1	1	2	mA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit	
R _{th(j-c)}	junction to case(AC)	TO-220A(Ins)	2.1		
		TO-220B(Non-Ins)/ TO-220C	1.2	°C/W	
		TO-220F(Ins)	2.3		
		TO-262	2.5		



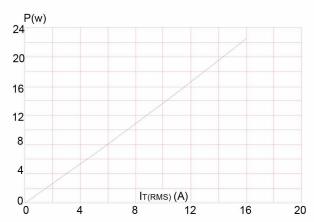


FIG.3: Surge peak on-state current versus number of cycles

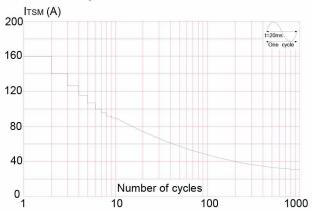
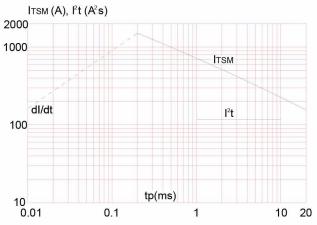


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I²t (dI/dt < 50A/µs)



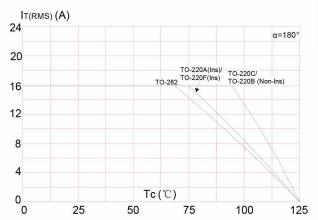


FIG.4: On-state characteristics (maximum values)

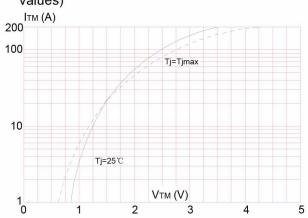


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature

